

Yulong Li

List of Publications by Year in descending order

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papers

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citations

236612

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288905

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99
all docs

99
docs citations

99
times ranked

1145
citing authors

#	ARTICLE	IF	CITATIONS
1	Intensity-modulated refractive index sensor based on the side modes of fiber Bragg grating. Optics Communications, 2022, 505, 127319.	1.0	16
2	Effects of Zn contents on microstructure, thermodynamic characteristic and mechanical properties of Sn-Bi-based lead-free solder. Journal of Materials Science: Materials in Electronics, 2022, 33, 1741-1751.	1.1	5
3	Enhancing the properties of the SAC305-soldered joint: heat treatment of the nickel-plated copper substrate before reflow soldering. Journal of Materials Science: Materials in Electronics, 2022, 33, 3535-3545.	1.1	5
4	Vacuum wetting of Ag/Ti2 to develop a novel micron porous Ti with significant biocompatibility and antibacterial activity. Journal of Materials Science and Technology, 2022, 116, 180-191.	5.6	12
5	Theoretical Modeling and Experimental Studies of Ultra-Thin Chip Transfer in Laser-Induced Forward Transfer. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2022, 12, 570-577.	1.4	2
6	Swirl-like Cu-Sn phase formation and the effects on the ultrasonic spot welded joint of Sn-coated Cu plates. Journal of Materials Processing Technology, 2021, 288, 116911.	3.1	10
7	Microstructure and mechanical properties of the Ni-B-Ti composite coating on Ti2 prepared by pre-plating and laser remelting. Surface and Coatings Technology, 2021, 405, 126567.	2.2	17
8	Preparation of high performance Fe-based amorphous coating by resistance seam welding. Surface and Coatings Technology, 2021, 408, 126813.	2.2	12
9	A novel method for fabricating micron-scale porous structure on the surface of commercially-pure Ti. Materials Letters, 2021, 294, 129802.	1.3	0
10	Wetting and Spreading of AgCuTi on Selective Laser-Melted Ti-6Al-4V. Materials, 2021, 14, 4804.	1.3	3
11	Interfacial reaction, wettability, and shear strength of ultrasonic-assisted lead-free solder joints prepared using Cu-GNSs-doped flux. Journal of Materials Science: Materials in Electronics, 2021, 32, 24507-24523.	1.1	13
12	Study on the performance of Cu foam with different porosity on SAC305 solder joints under ultrasonic-assisted soldering. Journal of Materials Science: Materials in Electronics, 2021, 32, 28108.	1.1	1
13	Microstructure and mechanical properties of laser fusion welded Al/steel joints using a Zn-based filler wire. Optics and Laser Technology, 2020, 122, 105882.	2.2	26
14	Microstructure and wear resistance of a Ni-WC composite coating on titanium grade 2 obtained by electroplating and electron beam remelting. Materials Characterization, 2020, 170, 110674.	1.9	33
15	Wetting Kinetics and Microstructure Analysis of BNi2 Filler Metal over Selective Laser Melted Ti-6Al-4V Substrate. Materials, 2020, 13, 4666.	1.3	3
16	An In-Situ Electroplating Fabricated Fabry-Perot Interferometric Sensor and Its Temperature Sensing Characteristics. Coatings, 2020, 10, 1174.	1.2	4
17	Wetting and spreading behaviors of Al-Si alloy on surface textured stainless steel by ultrafast laser. Applied Surface Science, 2020, 520, 146316.	3.1	28
18	Effect of temperature and substrate surface roughness on wetting behavior and interfacial structure between Sn-35Bi-1Ag solder and Cu substrate. Journal of Materials Science: Materials in Electronics, 2020, 31, 4224-4236.	1.1	10

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19	Cost-affordable, high-performance Tiâ€“TiB composite for selective laser melting additive manufacturing. <i>Journal of Materials Research</i> , 2020, 35, 1922-1935.	1.2	15
20	A Fiber Bragg Grating Sensing Structure for the Design, Simulation and Stress Strain Monitoring of Human Puncture Surgery. <i>Sensors</i> , 2019, 19, 3066.	2.1	4
21	Interfacial IMC Growth and Nanomechanical Characterizations of Solder in Sn-16Sb/Cu Joints during Solid-state Aging. <i>Journal Wuhan University of Technology, Materials Science Edition</i> , 2019, 34, 1210-1219.	0.4	1
22	Real-time in situ monitoring of internal stress of the electroplating processes using FBG sensors. <i>Applied Physics A: Materials Science and Processing</i> , 2019, 125, 1.	1.1	2
23	Microstructure evolution and wettability of Ag Cu Zn alloy on TiC Ni cermet. <i>Vacuum</i> , 2019, 159, 500-506.	1.6	4
24	Wetting kinetics and spreading phenomena of the precursor film and bulk liquid in the AgCuTi/TC4 system. <i>Journal of Alloys and Compounds</i> , 2019, 802, 345-354.	2.8	34
25	Wetting kinetics and interfacial structure of AgCu alloy spreading on TB8 substrates. <i>Materials Research Express</i> , 2019, 6, 0865e8.	0.8	2
26	Influence of Bi Addition on Pure Sn Solder Joints: Interfacial Reaction, Growth Behavior and Thermal Behavior. <i>Journal Wuhan University of Technology, Materials Science Edition</i> , 2019, 34, 668-675.	0.4	4
27	Laser 3D Printing of Fe-Based Bulk Metallic Glass: Microstructure Evolution and Crack Propagation. <i>Journal of Materials Engineering and Performance</i> , 2019, 28, 3478-3486.	1.2	11
28	Heat input, intermetallic compounds and mechanical properties of Al/steel cold metal transfer joints. <i>Journal of Materials Processing Technology</i> , 2019, 272, 40-46.	3.1	58
29	Microstructure and mechanical properties of Ti-6Al-4V prepared by nickel preplating and electron beam surface remelting. <i>Journal of Materials Processing Technology</i> , 2019, 271, 420-428.	3.1	33
30	Significant Inhibition of IMCs Growth between an Electroless Ni-W-P Metallization and SAC305 Solder During Soldering and Aging. <i>Journal Wuhan University of Technology, Materials Science Edition</i> , 2019, 34, 165-175.	0.4	4
31	Mechanical properties of CoSn ₂ and Î±-CoSn ₃ intermetallic compounds: first-principles calculations and nano-indentation measurements. <i>Applied Physics A: Materials Science and Processing</i> , 2019, 125, 1.	1.1	6
32	Effect of Bi on microstructure and mechanical properties of Sn-10Sb-1.5Cu (SSC1015) solder alloys. <i>Materials Research Express</i> , 2019, 6, 026565.	0.8	0
33	Growth behavior of IMCs layer of the Snâ€“35Biâ€“1Ag on Cu, Niâ€“P/Cu and Niâ€“Coâ€“P/Cu substrates during aging. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 1519-1530.	1.1	12
34	Effects of germanium on the microstructural, mechanical and thermal properties of Sn-0.7Cu solder alloy. <i>Materials Research Express</i> , 2019, 6, 016556.	0.8	5
35	Influences of Mono-Ni(P) and Dual-Cu/Ni(P) Plating on the Interfacial Microstructure Evolution of Solder Joints. <i>Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science</i> , 2019, 50, 480-492.	1.1	90
36	Research on Interfacial Reaction and Growth Behavior of Intermetallic Compound of Dip-Soldered Sn/Ni System. <i>Transactions of the Indian Institute of Metals</i> , 2019, 72, 651-661.	0.7	1

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37	Experimental Study and Fractal Analysis on the Anisotropic Performance of Explosively Welded Interfaces of 304 Stainless Steel/245 Carbon Steel. <i>Journal of Materials Engineering and Performance</i> , 2018, 27, 2556-2565.	1.2	4
38	Laser welding/brazing of 5182 aluminium alloy to ZEK100 magnesium alloy using a nickel interlayer. <i>Science and Technology of Welding and Joining</i> , 2018, 23, 543-550.	1.5	35
39	Influence of alloy elements on microstructure and mechanical properties of Al/steel dissimilar joint by laser welding/brazing. <i>Welding in the World, Le Soudage Dans Le Monde</i> , 2018, 62, 427-433.	1.3	42
40	Effect of Ni addition to the Cu substrate on the interfacial reaction and IMC growth with Sn3.0Ag0.5Cu solder. <i>Applied Physics A: Materials Science and Processing</i> , 2018, 124, 1.	1.1	25
41	Effects of thermal aging on growth behavior of interfacial intermetallic compound of dip soldered Sn/Cu joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 8863-8875.	1.1	13
42	Interfacial reaction between liquid-state Sn-xBi solder and Co substrate. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 9155-9165.	1.1	6
43	Effect of Ni Addition to Sn0.7Cu Solder Alloy on Thermal Behavior, Microstructure, and Mechanical Properties. <i>Journal of Materials Engineering and Performance</i> , 2018, 27, 6564-6576.	1.2	9
44	Temperature sensing characteristics of metal coated FBG during dynamic cooling process. <i>Optical Fiber Technology</i> , 2018, 45, 368-375.	1.4	17
45	Effects of In addition on the wettability, interfacial characterization and properties of ternary Sn-Cu-Ni solders. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 18840-18851.	1.1	7
46	Effect of electroplating parameters on electroplated Cu film and microvoid formation of solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 18404-18416.	1.1	7
47	Shear strength and fracture surface analysis of Sn58Bi/Cu solder joints under a wide range of strain rates. <i>Microelectronics Reliability</i> , 2018, 86, 27-37.	0.9	19
48	Wetting kinetics and spreading phenomena of Sn-35Bi-1Ag solder on different substrates. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 13914-13924.	1.1	11
49	Diode Laser Welding/Brazing of Aluminum Alloy to Steel Using a Nickel Coating. <i>Applied Sciences (Switzerland)</i> , 2018, 8, 922.	1.3	19
50	Blind MuseumTourer: A System for Self-Guided Tours in Museums and Blind Indoor Navigation. <i>Technologies</i> , 2018, 6, 4.	3.0	59
51	Interfacial Reaction and IMC Growth of an Ultrasonically Soldered Cu/SAC305/Cu Structure during Isothermal Aging. <i>Materials</i> , 2018, 11, 84.	1.3	15
52	Effect of Cu6Sn5 nanoparticle on thermal behavior, mechanical properties and interfacial reaction of Sn3.0Ag0.5Cu solder alloys. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 15983-15993.	1.1	18
53	Interfacial microstructure evolution and shear strength of Sn0.7Cu-xNi/Cu solder joints. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 11314-11324.	1.1	21
54	Interfacial IMC growth of SAC305/Cu joint with a novel dual-layer of Ni(P)/Cu plating during solid-state aging. <i>Microelectronic Engineering</i> , 2018, 199, 69-79.	1.1	13

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55	Interfacial reaction and microstructure between the Sn ₃ Ag _{0.5} Cu solder and Cu-Co dual-phase substrate. <i>Applied Physics A: Materials Science and Processing</i> , 2018, 124, 1.	1.1	14
56	Metal coatings on long-period fiber gratings and the implementation of an associated sensing model. <i>Applied Physics A: Materials Science and Processing</i> , 2017, 123, 1.	1.1	3
57	Theoretical and experimental study of macrobending losses in coated single-mode fibers. <i>Optical Engineering</i> , 2017, 56, 066102.	0.5	5
58	The growth behavior of interfacial intermetallic compound between Sn-3.5Ag-0.5Cu solder and Cu substrate under different thermal-aged conditions. <i>Journal of Materials Science: Materials in Electronics</i> , 2017, 28, 18515-18528.	1.1	27
59	Influence of Zn additions on the interfacial reaction and microstructure of Sn ₃₇ Pb/Cu solder joints. <i>Applied Physics A: Materials Science and Processing</i> , 2017, 123, 1.	1.1	5
60	Fabrication, microstructure, and wear performance of WC-Fe composite/metal coating fabricated by resistance seam welding. <i>Materials Characterization</i> , 2017, 134, 182-193.	1.9	23
61	Light intensity modulation temperature sensor based on U-shaped bent single-mode fiber. <i>Optik</i> , 2017, 130, 813-817.	1.4	17
62	Shear strength and fracture behavior of reflowed Sn _{3.0} Ag _{0.5} Cu/Cu solder joints under various strain rates. <i>Journal of Alloys and Compounds</i> , 2017, 690, 720-729.	2.8	86
63	Comparative study of wear performance of ceramic/iron composite coatings under two different wear modes. <i>Surface and Coatings Technology</i> , 2017, 309, 136-148.	2.2	14
64	Effects of post-reflow cooling rate and thermal aging on growth behavior of interfacial intermetallic compound between SAC305 solder and Cu substrate. <i>Applied Physics A: Materials Science and Processing</i> , 2016, 122, 1.	1.1	23
65	Microstructure evolution and shear fracture behavior of aged Sn ₃ Ag _{0.5} Cu/Cu solder joints. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2016, 673, 167-177.	2.6	124
66	A study of the microstructure, thermal properties and wetting kinetics of Sn-3Ag-xZn lead-free solders. <i>Applied Physics A: Materials Science and Processing</i> , 2016, 122, 1.	1.1	1
67	Simulation and experiment of packaging of the fibre Bragg grating sensors using brazing/soldering methods. <i>Journal of Modern Optics</i> , 2016, 63, 1414-1419.	0.6	2
68	Temperature and strain sensing properties of the zinc coated FBG. <i>Optik</i> , 2016, 127, 6463-6469.	1.4	28
69	An Electroplating Method for Surface Mounting Optical Fiber Sensors on the Metal Substrate. <i>IEEE Photonics Technology Letters</i> , 2016, 28, 1811-1814.	1.3	10
70	Interfacial reaction and IMCs growth behavior of Sn ₃ Ag _{0.5} Cu/Ni solder bump during aging at various temperatures. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 4245-4252.	1.1	14
71	Effects of metal coating on the fiber Bragg grating temperature sensing characteristics. <i>Journal of Modern Optics</i> , 2016, 63, 762-770.	0.6	10
72	Wetting kinetics of the AgCuTi filler metal on pure molybdenum substrate. <i>Surface and Interface Analysis</i> , 2015, 47, 838-843.	0.8	4

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73	A study on the interfacial reaction of Sn58Bi/Cu soldered joints under various cooling and aging conditions. Journal of Materials Science: Materials in Electronics, 2015, 26, 5140-5151.	1.1	11
74	Effect of alloying Cu substrate on microstructure and coarsening behavior of Cu6Sn5 grains of soldered joints. Journal of Materials Science: Materials in Electronics, 2015, 26, 2782-2794.	1.1	9
75	Dissimilar Laser Welding/Brazing of 5754 Aluminum Alloy to DP 980 Steel: Mechanical Properties and Interfacial Microstructure. Metallurgical and Materials Transactions A: Physical Metallurgy and Materials Science, 2015, 46, 5149-5157.	1.1	57
76	Developments of high strength Bi-containing Sn0.7Cu lead-free solder alloys prepared by directional solidification. Journal of Alloys and Compounds, 2015, 625, 241-250.	2.8	69
77	Effect of strain rate on interfacial fracture behaviors of Sn-58Bi/Cu solder joints. Journal of Materials Science: Materials in Electronics, 2014, 25, 57-64.	1.1	21
78	Mechanical response of reaction phases of the TiAl/steel brazed joint under a tensile load. Journal of Materials Science, 2014, 49, 1114-1120.	1.7	3
79	Interfacial reaction and IMC growth between Bi-containing Sn0.7Cu solders and Cu substrate during soldering and aging. Journal of Alloys and Compounds, 2014, 582, 341-347.	2.8	77
80	Capillary encapsulating of fiber Bragg grating and the associated sensing model. Optics Communications, 2014, 333, 92-98.	1.0	9
81	Tensile properties of Cu/Sn58Bi/Cu soldered joints subjected to isothermal aging. Journal of Materials Science: Materials in Electronics, 2014, 25, 2416-2425.	1.1	20
82	Shear strengths and fracture behaviors of Cu/Sn37Pb/Cu soldered joints subjected to different displacement rates. Journal of Alloys and Compounds, 2014, 600, 13-20.	2.8	23
83	Microstructure and shear strength of Sn37Pb/Cu solder joints subjected to isothermal aging. Microelectronics Reliability, 2014, 54, 1575-1582.	0.9	53
84	Interfacial reaction and growth behavior of IMCs layer between Sn58Bi solders and a Cu substrate. Journal of Materials Science: Materials in Electronics, 2013, 24, 2027-2034.	1.1	34
85	Dissolution of TiAl alloy during high temperature brazing. Journal of Materials Science, 2013, 48, 5247-5252.	1.7	18
86	Effect of Bi Segregation on the Asymmetrical Growth of Cu-Sn Intermetallic Compounds in Cu/Sn-58Bi/Cu Sandwich Solder Joints During Isothermal Aging. Journal of Electronic Materials, 2013, 42, 3567-3572.	1.0	15
87	Reactive wetting of AgCuTi filler metal on the TiAl-based alloy substrate. Applied Surface Science, 2012, 259, 343-348.	3.1	33
88	Simultaneous measurement of the temperature and force using a steel cantilever soldered with a partially nickel coated in-fibre Bragg grating. Optics Communications, 2012, 285, 4275-4279.	1.0	15
89	Preferential spreading of molten metal over an anisotropically microstructured surface. Europhysics Letters, 2012, 97, 46003.	0.7	7
90	Ultrasonic embedding of nickel-coated fiber Bragg grating in aluminum and associated sensing characteristics. Optical Fiber Technology, 2012, 18, 7-13.	1.4	52

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91	Ultrahigh-temperature Nbss/Nb5Si3 fully-lamellar microstructure developed by directional solidification in OFZ furnace. <i>Intermetallics</i> , 2011, 19, 460-469.	1.8	45
92	Capillary Rise of Liquids over a Microstructured Solid Surface. <i>Langmuir</i> , 2011, 27, 14260-14266.	1.6	36
93	Microstructural evolution of unidirectionally solidified NbSS-Nb5Si3 eutectic alloy. <i>Rare Metals</i> , 2011, 30, 335-339.	3.6	7
94	Mechanical properties of directionally solidified Nbâ€“Moâ€“Si-based alloys with aligned Nbss/Nb5Si3 lamellar structure. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2011, 528, 5772-5777.	2.6	47
95	Thermal Process Analysis in Welding Prototyping of Metal Structures. <i>Lecture Notes in Electrical Engineering</i> , 2011, , 383-390.	0.3	1
96	Mechanical response of the TiAl/steel brazed joint under impact load. <i>Journal of Materials Science</i> , 2009, 44, 3077-3081.	1.7	2
97	Metal coating of fiber Bragg grating and the temperature sensing character after metallization. <i>Optical Fiber Technology</i> , 2009, 15, 391-397.	1.4	81
98	The complete sequence of mitochondrial COII gene of Fenneropenaeus chinensis and its applicability as a marker for phylogenetic analysis. <i>Journal of Ocean University of China</i> , 2007, 6, 187-192.	0.6	1
99	Interface structure and mechanical properties of the TiAl/42CrMo steel joint vacuum brazed with Agâ€“Cu/Ti/Agâ€“Cu filler metal. <i>Scripta Materialia</i> , 2006, 55, 171-174.	2.6	45